

Title (en)

Thermosiphon cooler arrangement in modules with electric and/or electronic components

Title (de)

Thermosiphon-Kühleranordnung in Modulen mit elektrischen und/oder elektronischen Komponenten

Title (fr)

Agencement de refroidisseur à thermosiphon dans des modules avec des composants électriques ou électroniques

Publication

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Application

EP 12188563 A 20121015

Priority

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Abstract (en)

The present invention relates to the cooling of electric and/or electronic components, in particular to a module (102) of an electric and/or electronic system. The module (102) comprising a guiding structure (615) and an inlet (614) for receiving a stream of cooling air and with an outlet (616) for releasing cooling air thereafter in an operating state of the module (102). The guiding structure (615) being provided for guiding the cooling air entering through the inlet (614) and leaving the module through the outlet (616) in an operating state of the module (102). The module (102) comprises a thermosiphon cooler (600) with an evaporator (604) and a condenser (602) for transferring a majority of a heat load to said cooling air in an operating state of the module (102). The evaporator (604) is tilted with respect to the condenser (602) wherein the condenser (602) is arranged such that a major portion of said cooling air flows through the condenser (602).

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Citation (applicant)

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